


APPLICATION DATA SHEET

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Title of Invention	Method for Manufacturing Buried Insulating Layer Type Single Crystal Silicon Carbide Substrate and Manufacturing Device for the Same		
Application Type : regular, utility Attorney Docket Number : 040091			
Correspondence address: Customer Number: 23850			
			
Priority Data: Doc.No: 2003-84056; Country -JP ; Date: 2003-03-26 us-priority-claimed			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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